

TITLE: Microelectronic Die Providing Improved Heat Dissipation and Method of Packaging Same
INVENTOR(S): Crippen
DOCKET NO.: P12659

REPLACEMENT SHEET

36

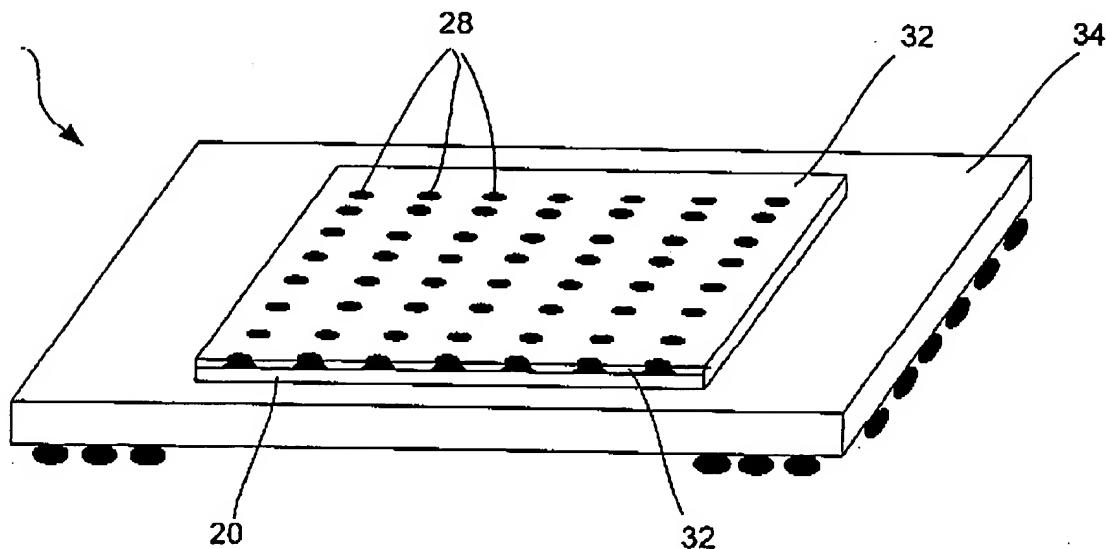


Fig. 8

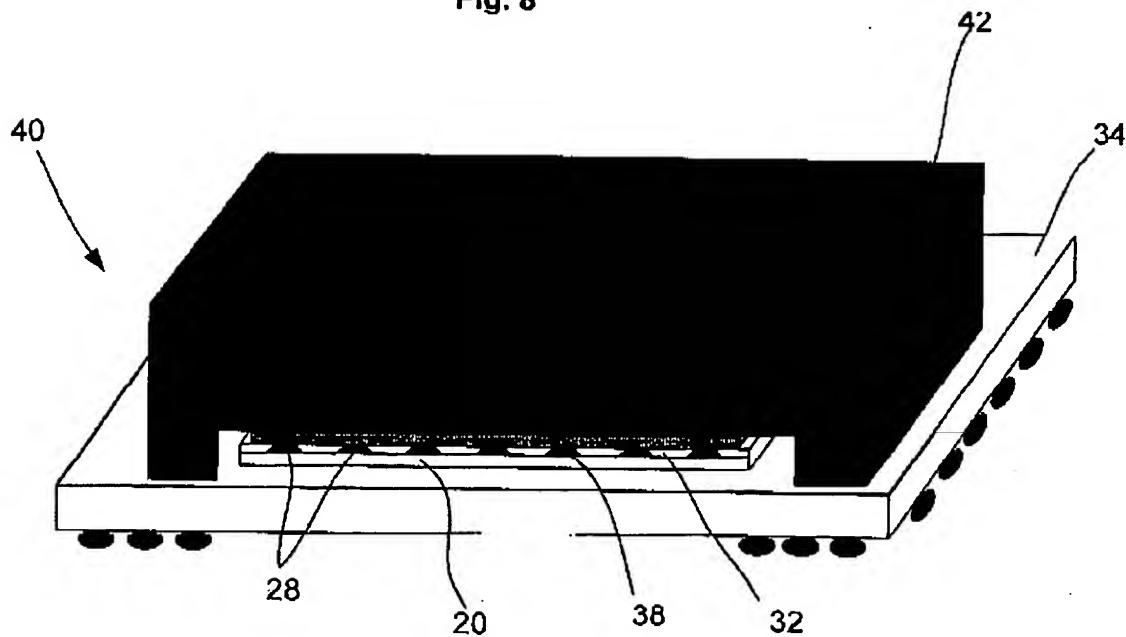


Fig. 9